[0007a] In a first aspect, there is provided a method of producing a polishing pad, comprising:

providing a mold, having a first cavity and a second cavity, wherein said first cavity defines a recess;

providing a polymer matrix material including void forming elements in said recess;

forming a polishing pad and removing at least a portion of said elements from said polishing pad forming void spaces within said polishing pad by one of a chemical method or mechanical method, prior to use in chemical/mechanical planarization procedures.

[0007b] In another aspect, there is provided a device for polishing, comprising:
a pad manufactured in accordance with the method as defined above, said pad comprising a polymer matrix having a plurality of voids defined within said polymer matrix, wherein said voids have a length to diameter ratio of 4:1 or greater and said voids are at least partially interconnected.

[0007c] In another aspect, there is provided a method of polishing, comprising:
providing a substrate for polishing having a surface;
providing an aqueous slurry on at least a portion of said surface of said substrate;
providing a pad manufactured in accordance with the method as defined above, said pad comprising a polymer matrix having a plurality of voids defined therein, wherein said voids have a length to diameter ratio of 4:1 or greater and said voids are at least partially interconnected; and
polishing said surface by the interaction of said substrate, said aqueous slurry and said pad.

[0007d] In another aspect, there is provided a polishing pad manufactured in accordance with the method as defined above, said polishing
pad being for polishing a surface of an electronic substrate and comprising a polymeric matrix including voids, wherein said pad has a first working surface for polishing a working surface and a second surface;
said pad having a thickness **T** extending from said working surface to said second surface;
wherein said polishing pad includes a region where said voids are uniformly distributed, and a region where said voids are not present, wherein said region where said voids are not present comprises at least 5.0% of the pad volume.

~~21. A polishing pad for polishing a surface of an electronic substrate, comprising~~

~~a polymeric matrix including voids, wherein said pad has a first working surface for polishing a working surface and a second surface;~~

~~said pad having a thickness T extending from said working surface to said second surface; wherein said voids are located only in a region from said pad surface to a thickness of 0.95(T).~~

~~22. The polishing pad of claim 21 wherein said voids wherein said voids have a length to diameter ratio of 4:1 or greater and said voids are at least partially interconnected.~~

~~23. The polishing pad of claim 21 wherein said voids are located only in a region from said pad surface to a thickness of 0.50(T).~~

~~24. The polishing pad of claim 21 wherein said voids have a diameter of 0.1 μm or greater.~~

~~25. The polishing pad of claim 21 wherein said voids are uniformly distributed in that region where said voids are located.~~

21~~26~~. A polishing pad manufactured in accordance with the method of claim 1, said polishing p~~b~~ad being for polishing a surface of an electronic substrate and comprising a polymeric matrix including voids, wherein said pad has a first working surface for polishing a working surface and a second surface;

said pad having a thickness **T** extending from said working surface to said second surface; wherein said polishing pad includes a region where said voids are uniformly distributed, and a region where said voids are not present, wherein said region where said voids are not present comprises at least 5.0% of the pad volume.